USPTO Patent Full-Text and Image Database

Searching US Patent Collection...

Results of Search in US Patent Collection db for:
AN/"Brewer Science": 175 patents.
*Hits **1** through **50** out of **175***

Next 50 Hits

Jump To

Refine Search AN/"Brewer Science"

	PAT. NO.	Title
1	11,078,337	High-.chi. block copolymers for directed self-assembly
2	10,968,348	Laser-releasable bonding materials for 3-D IC applications
3	10,961,383	Gradient block copolymers for directed self-assembly
4	10,854,451	Superplanarizing spin-on carbon materials
5	10,770,813	Environmentally sealed, reusable connector for printed flexible electronics
6	10,734,239	High-chi block copolymers with tunable glass transition temperatures for directed self-assembly
7	10,617,010	Polymer film stencil process for fan-out wafer-level packaging of semiconductor devices
8	10,519,333	Multifunctional alcohol dispersions of carbon nanotubes
9	10,421,878	High-Chi block copolymers for directed self-assembly
10	10,366,887	Method of using chemically patterned guide layers in chemoepitaxy directing of block co-polymers
11	10,352,726	Thin-film resistive-based sensor
12	10,331,032	Photosensitive, developer-soluble bottom anti-reflective coating material
13	10,329,451	All-organic high refractive index materials
14	10,317,291	Environmental sensor system and signal processor
15	10,304,720	Laser ablative dielectric material
16	10,103,048	Dual-layer bonding material process for temporary bonding of microelectronic substrates to carrier substrates
17	RE46,841	Spin-on carbon compositions for lithographic processing
18	9,960,038	Processes to pattern small features for advanced patterning needs
19	9,865,490	Cyclic olefin polymer compositions and polysiloxane release layers for use in temporary wafer bonding processes
20	9,827,757	Methods of transferring device wafers or layers between carrier substrates and other surfaces
21	9,827,740	Polyimides as laser release materials for 3-D IC applications
22	9,738,805	Highly soluble carbon nanotubes with enhanced conductivity

23	9,728,439		High-temperature, spin-on, bonding compositions for temporary wafer bonding using sliding approach
24	9,642,258	T	All-organic inductor-capacitor tank circuit for radio frequency sensor applications
25	9,640,396	T	Spin-on spacer materials for double- and triple-patterning lithography
26	9,638,999	T	Dual-layer light-sensitive developer-soluble bottom anti-reflective coatings for 193-nm lithography
27	D785,058	T	Spin coater
28	D785,057	T	Bake plate
29	D783,692	T	Spin coater/developer
30	9,611,346	T	Highly crosslinked polymer dielectric films for improved capacitor performance
31	9,580,294	T	Computer program and method for verifying container of material to be dispensed
32	9,496,164	T	Cyclic olefin polymer compositions and polysiloxane release layers for use in temporary wafer bonding processes
33	9,482,951	T	Non-covalently crosslinkable materials for photolithography processes
34	9,472,436	T	Multiple bonding layers for thin-wafer handling
35	9,349,643	T	Apparatus and method for thin wafer transfer
36	9,328,246	T	Nonpolymeric antireflection compositions containing adamantyl groups
37	9,299,778	T	CVD-free, scalable processes for the production of silicon micro- and nanostructures
38	9,263,314	T	Multiple bonding layers for thin-wafer handling
39	9,249,013	T	Silicon hardmask layer for directed self-assembly
40	9,224,631	T	Multiple bonding layers for thin-wafer handling
41	9,157,003	T	Highly soluble carbon nanotubes with enhanced conductivity
42	9,127,126	T	Development of high-viscosity bonding layer through in-situ polymer chain extension
43	9,123,541	T	Highly etch-resistant polymer block for use in block copolymers for directed self-assembly
44	9,117,757	T	Silicone polymers with high refractive indices and extended pot life
45	9,111,981	T	Method for reversibly mounting a device wafer to a carrier substrate
46	9,110,372	T	Anti-reflective coatings using vinyl ether crosslinkers
47	9,102,129	T	Spin-on carbon compositions for lithographic processing
48	9,099,512	T	Article including a device wafer reversibly mountable to a carrier substrate
49	8,968,989	T	Assist layers for EUV lithography
50	8,940,104	T	Cleaning composition for temporary wafer bonding materials

Next List | Top | View Cart
Home | Quick | Advanced | Pat Num | Help